

Amendments to the Specification:

Please replace the title as follows:

~~WAFER-RETAINING CARRIER, DOUBLE-SIDE GRINDING DEVICE USING THE
SAME, AND DOUBLE-SIDE GRINDING METHOD FOR WAFER~~

WAFER-HOLDING CARRIER, DOUBLE-SIDE POLISHING APPARATUS USING THE
SAME, AND DOUBLE-SIDE POLISHING METHOD OF WAFER